

MB1-130-01-F-S-01-SL

MB1-130-01-F-S-01-SL-N

(1.00 mm) .0394"

MB1 SERIES

MINI EDGE CARD SOCKET WITH GUIDES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MB1

Insulator Material:

Black LCP

Contact Material:

BeCu

Plating:

Sn or Au over

50 μ" (1.27 μm) Ni

Current Rating:

2.4 A per pin

(2 pins powered)

Voltage Rating:

250 VDC/354 VDC

Operating Temp Range:

-55 °C to +125 °C

Insertion Depth:

(5.26 mm) .207" to

(6.10 mm) .240"

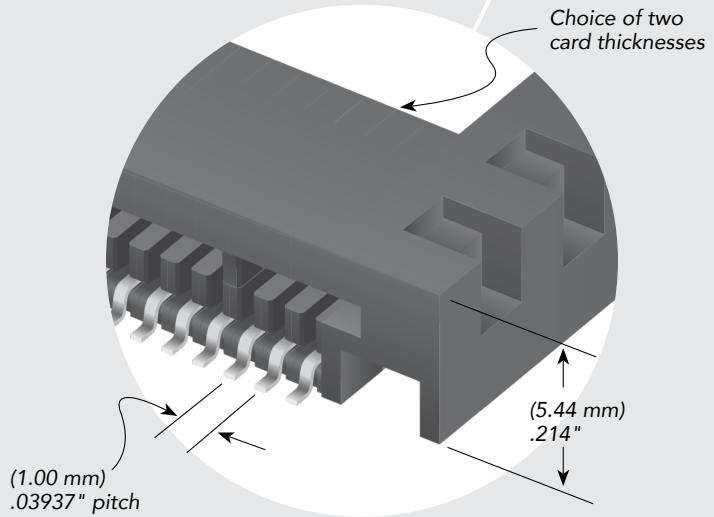
RoHS Compliant:

Yes

Mates with:

(0.80 mm) .031" PCB,

(1.60 mm) .062" PCB



PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (20-30)

(0.15 mm) .006" max (40-50)*

*(.004" stencil solution

may be available; contact

ipg@samtec.com)

RECOGNITIONS

For complete scope of

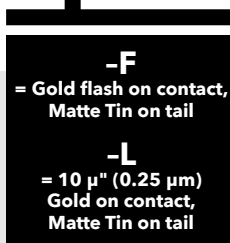
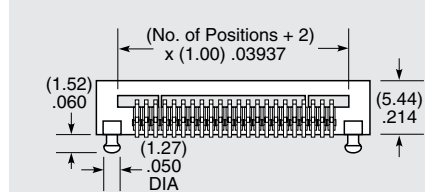
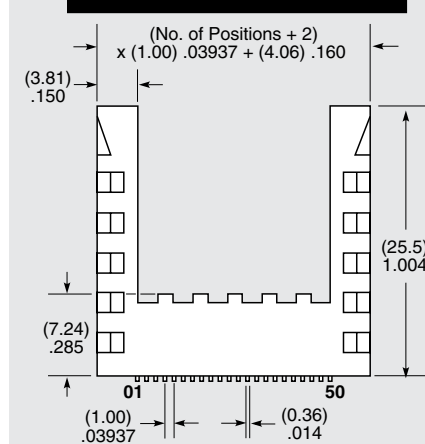
recognitions see

www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

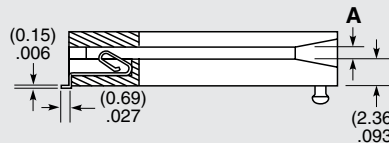
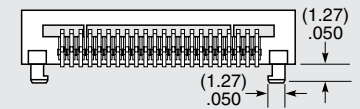
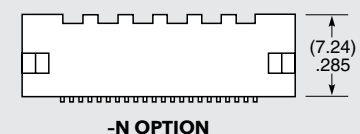
- Other platings



Specify CARD SLOT from chart

-N = No Card Guides

CARD SLOT	A	MATES WITH BOARD THICKNESS
-01	(0.97) .038	(0.80) .031
-02	(1.83) .072	(1.60) .062



Important Note: Samtec recommends that pads on the mating board be Gold plated.

Note: Some sizes, styles and options are non-standard, non-returnable.